

March 19, 2002

CN 031902

Customer Notification

Mold Compound and Die Attach Change for ETQFP Package DS3/E3/STS-1 LIU Framer

Dear Valued Customer:

This notification is for the purpose of informing you of a change by Conexant Systems/MINDSPEED Technologies in the package mold compound and die attach material used for the CX2833x-18 and M2833x-34 devices. Details of this change are described below.

Purpose

To utilize the standard mold compound and die attach material as recommended by our assembly subcontractor, Amkor, in the production of ETQFP packages. The change is as follows:

	<u>Original</u>	<u>New</u>
Mold compound	Sumitomo 7351UL	Sumitomo G700
Die attach	Ablestik 8361J	Ablestik 3230

Change Schedule

Customers should expect to receive products with the new mold compound and die attach in late Q2, CY02.

Method to identify parts

The products with the new mold compound will be identifiable by date code. This information will be available upon request.

Customer Impact

There are no changes to performance of the device. The new mold compound and die attach have been qualified by Mindspeed Technologies. Qualification information is available upon request.

We are confident this change will allow Conexant Systems/MINDSPEED Technologies to maintain its high standards for quality and reliability. We will be managing this change very closely to ensure minimum disruption to our customers. If, at any time, you have a need for further information, please contact your local Sales Representative.

